



Thermal Interface Material X-23-7868-2D

PRODUCT DESCRIPTION

Package temperature constraints can severely limit a power device's performance. Both the performance reliability and life expectancy are inversely related to the device temperature. Shin-Etsu MicroSi's X23-7868-2D is an ideal thermal interface material for high performance based platforms.

PROPERTIES

Property

Viscosity @ 25°C(Pascal Second)	100/680 (per/post application)
Appearance	Gray
Volatile Content after 24hrs. at 150°C (%)	2.8
Specific Gravity	2.6

Packaging Description

Thermal Grease X-23-7868-2D is available in:

Syringes:	0.5 gm, 1.0 gm, 1.5 gm,
Cartridges:	55 gm, 150 gm, 400 gm
Bulk:	1.0 Kg
Custom Sizes Available	
Storage Conditions:	60°F to 85°F

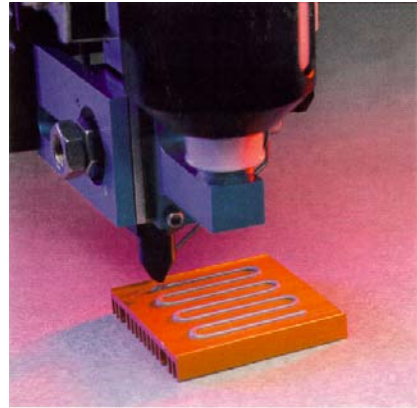
APPLICATION

Evaluation: Uniform Thickness Approach: 1) Review the provided MSDS. 2) Remove any existing thermal interface material from the test fixture, if present. 3) Using an adhesive tape, box out a square section on the heatsink that is equal to, if not slightly larger than the processor. 4) In a well ventilated environment place the contents of the sample syringe in a dollop form, at the center of the heatsink. 5) Using a flat, straight edge, spread the material in such a manner that the material is equally spread out over the exposed surface of the heatsink. The thinner the material the better. 6) Once a uniform thickness is achieved, remove the adhesive tape, in such a manner that the thermal interface material remains on the heatsink. 7) **Please note that these materials contain an application chemical that needs to be removed for optimal performance.** If possible, allow the heatsink to sit exposed overnight, to allow the application chemical to evaporate. 8) Evaluate the material in the assembly, until the thermal resistance value has stabilized.

Dollop Pattern Approach: 1) Review the provided MSDS. 2) Remove any existing thermal interface material from the test fixture, if present. 3) In a well ventilated environment place approximately half of the contents of the sample syringe in a dollop form, at the center of the heatsink. 4) Reassemble the test fixture in such a manner that the thermal interface material is distributed across the chip surface and heatsink. 5) **Please note that these materials contain an application chemical that needs to be removed for optimal performance.** This can be accomplished by operating the assembly in an open environment. 6) Evaluate the material in the assembly, until the thermal resistance value has stabilized.

Thermal Interface Material X-23-7868-2D

For medium to large production applications, Shin-Etsu MicroSi can provide X-23-7868-2D in cartridges. The cartridge delivery system can be utilized with either manual, automated or silk-screening equipment. The cartridge delivery system allows dispensing of the material, while protecting the integrity and exposure level of the unused portion.



Bulk delivery provides the lowest possible unit cost. Bulk purchases are available for large scale production facilities where material is consumed at a rapid rate.

The information given herein is based on data believed to be reliable, but Shin-Etsu MicroSi, Inc. makes no warranties expressed or implied as to its accuracy and assumes no liability arising out of its use by others. This publication is not to be taken as a license to operate under, or recommendation to infringe upon any patent.